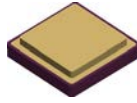


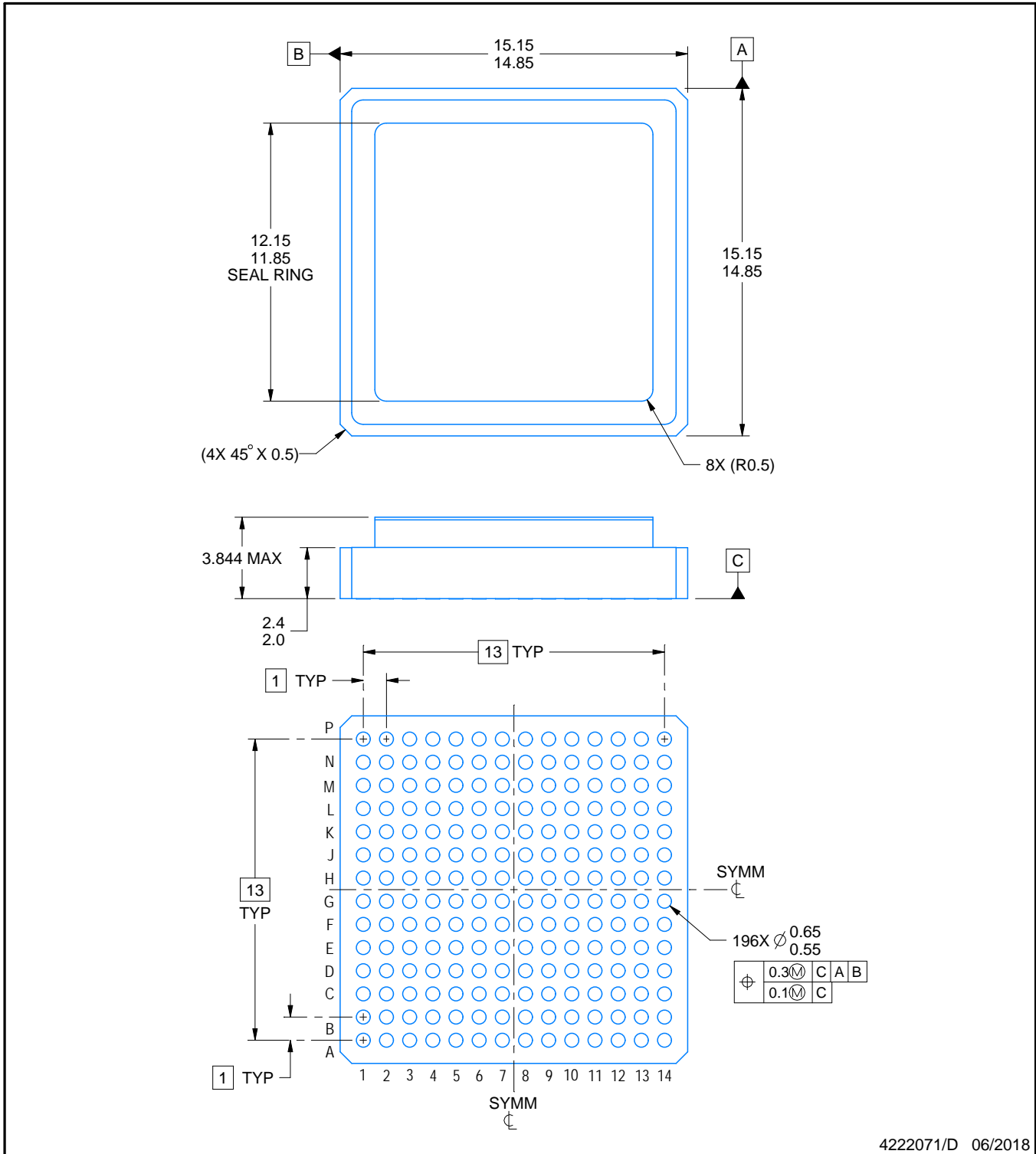
# ZMX0196A



# PACKAGE OUTLINE

## CLGA - 3.844 mm max height

Ceramic Land Grid Array



4222071/D 06/2018

**NOTES:**

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.

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